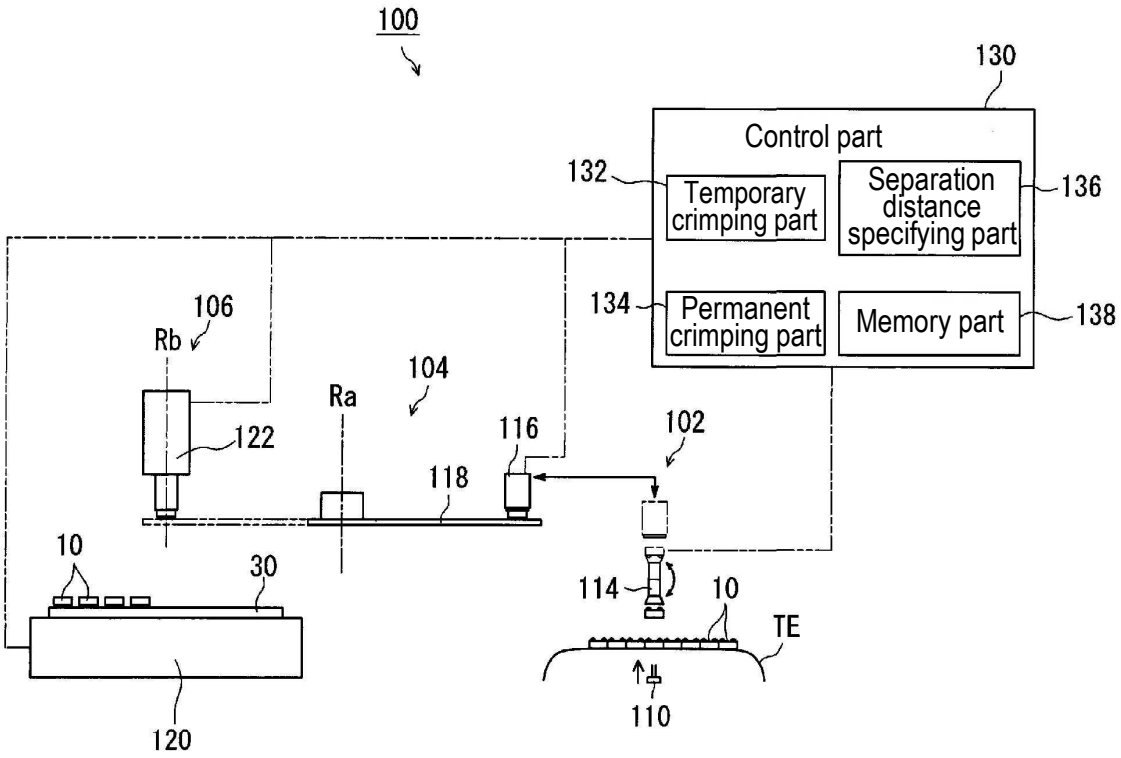
100
130
Control part
132
Temporary crimping part
Separation distance specifying part
136
134
Permanent crimping part
Memory part
138
106
Rb
104
Ra
122
116
102
118
10
30
114
10
TE
110
120

FIG. 1

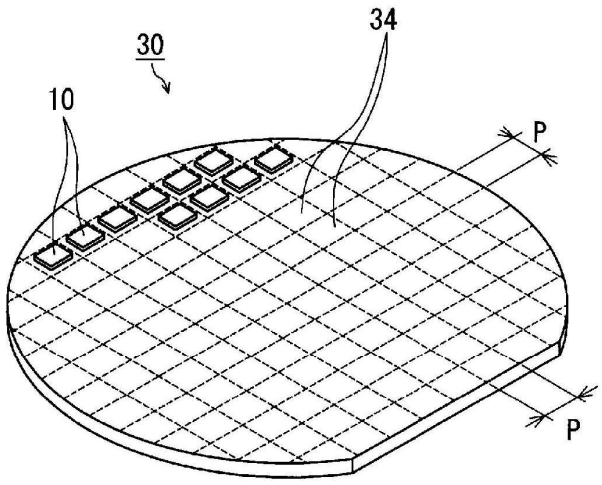
30
34
10
P
P

FIG. 2

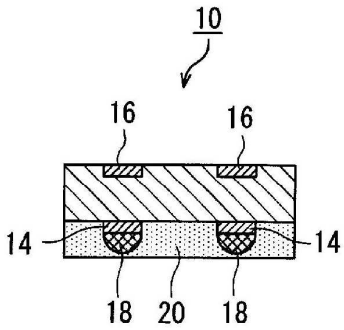

FIG. 3

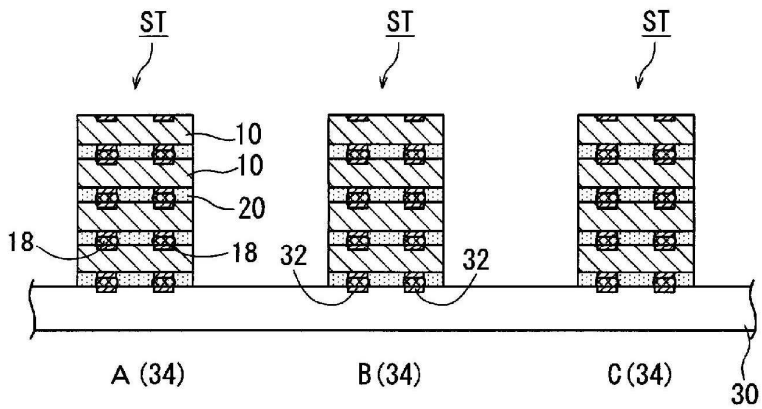

FIG. 4

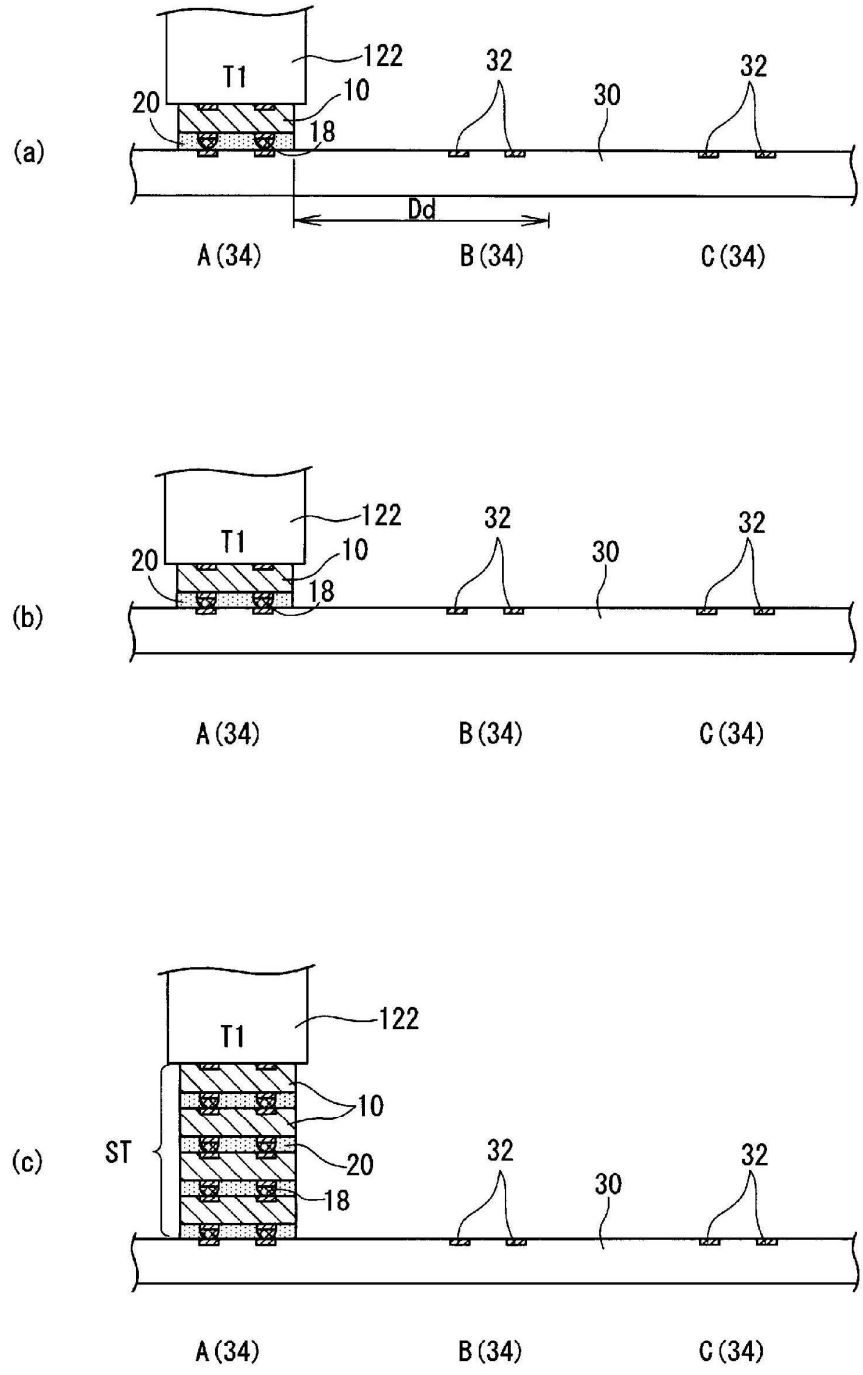
(a)
T1
122
32
32
20
10
30
18
Dd
A (34)
B (34)
C (34)
(b)
T1
122
32
32
20
10
30
18
A (34)
B (34)
C (34)
(c)
T1
122
ST
10
20
32
32
30
18
A (34)
B (34)
C (34)

FIG. 5

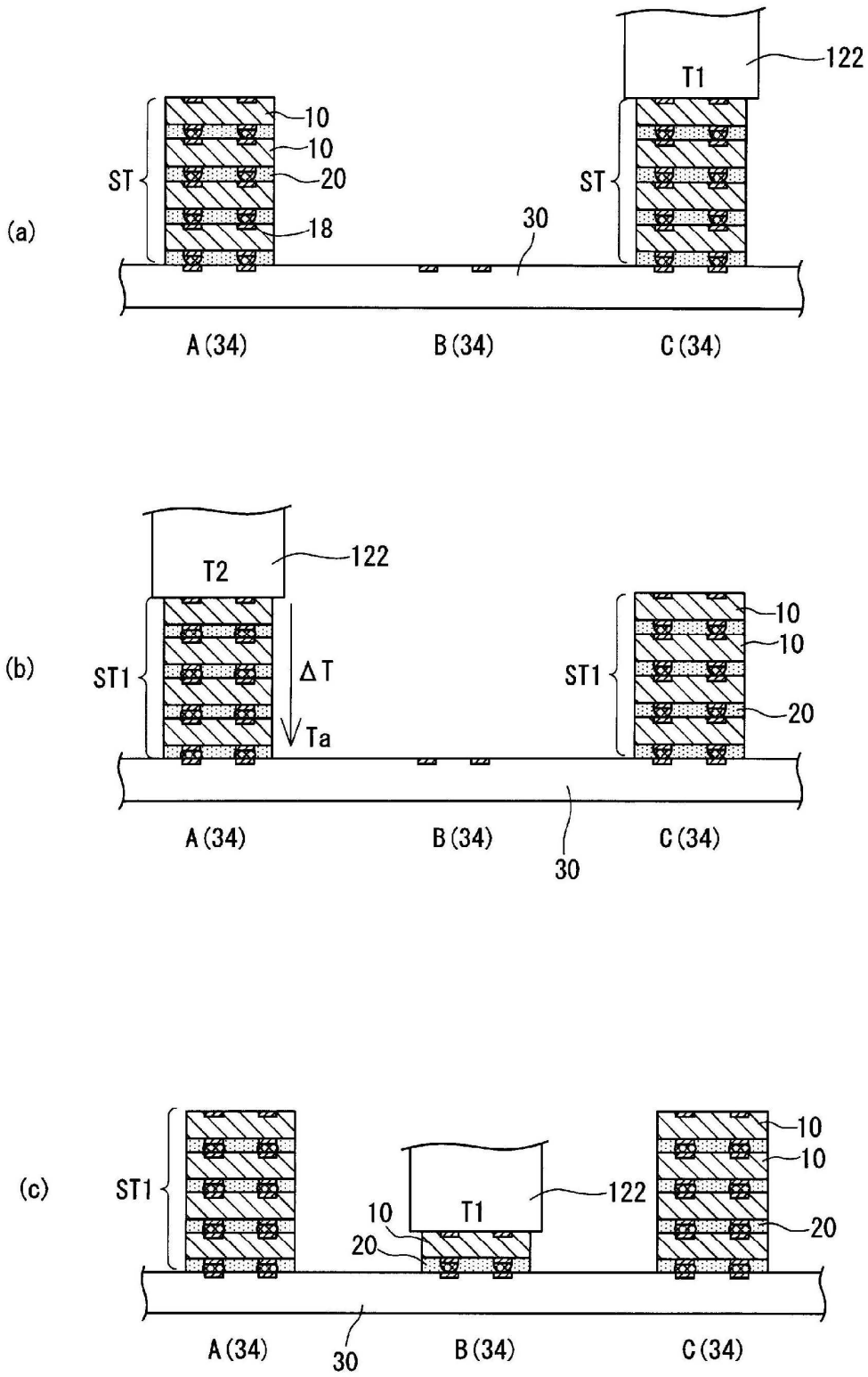
(a)
T1
122
10
10
20
18
ST
ST
30
A (34)
B (34)
C (34)
(b)
T2
122
ΔT
Ta
ST1
ST1
10
10
20
30
A (34)
B (34)
C (34)
(c)
ST1
10
T1
122
20
10
10
20
A (34)
30
B (34)
C (34)

FIG. 6

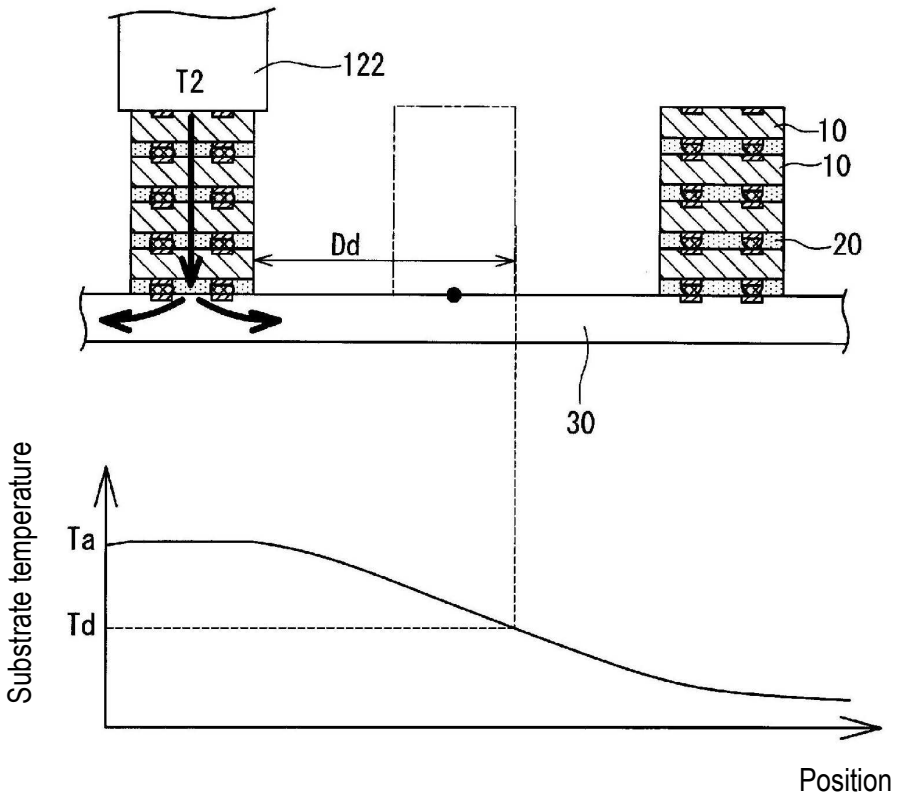
T2
122
10
10
20
Dd
30
Substrate temperature
Ta
Td
Position

FIG. 7

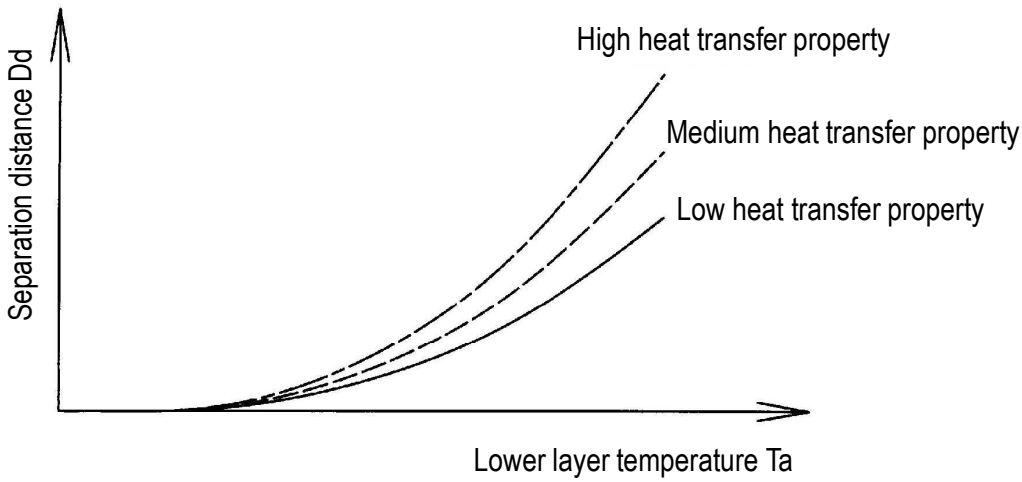
High heat transfer property
Medium heat transfer property
Low heat transfer property
Separation distance Dd
Lower layer temperature Ta

FIG. 8

Material \ Thickness	* * *	* * *	* * *
* * *	High	High	Low
* * *	High	Medium	Low
⋮	⋮	⋮	⋮
* * *	Medium	Medium	Low

FIG. 9

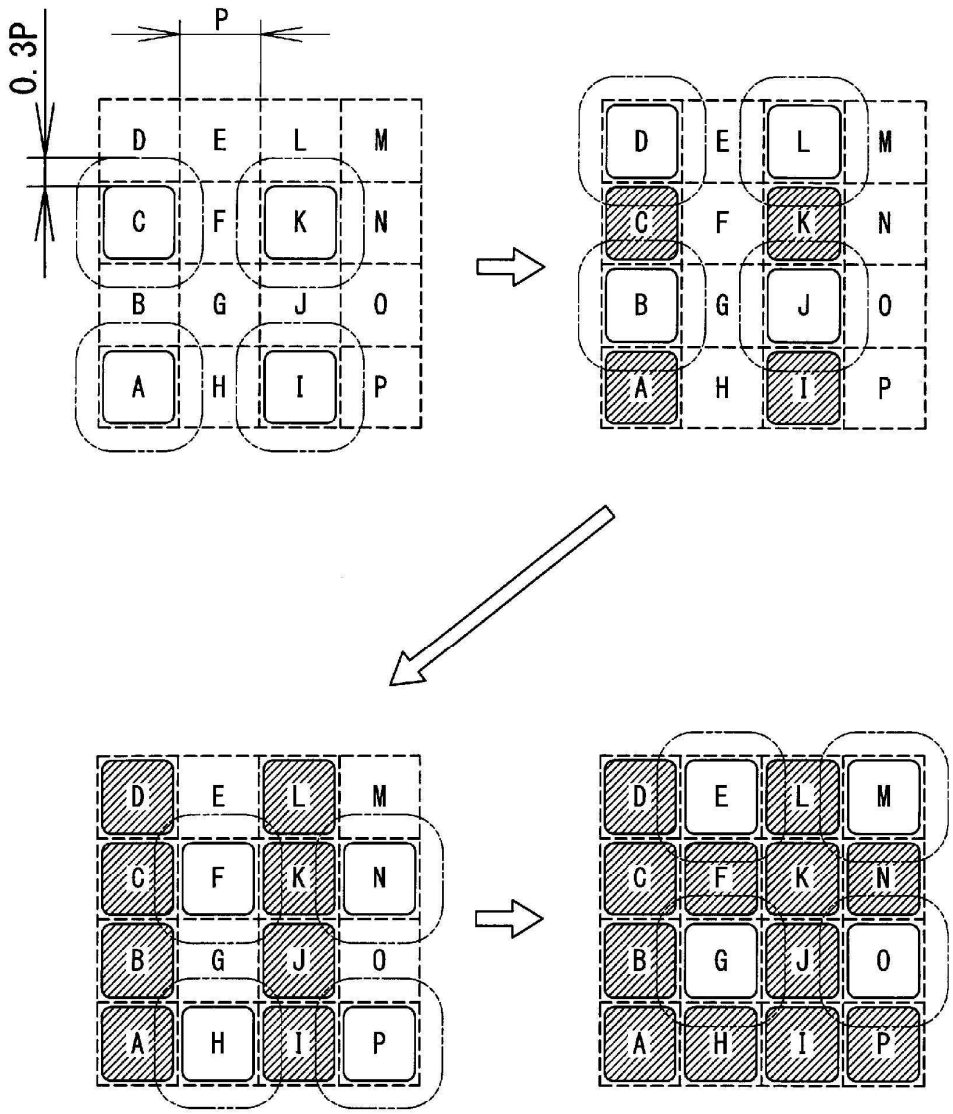

FIG. 10

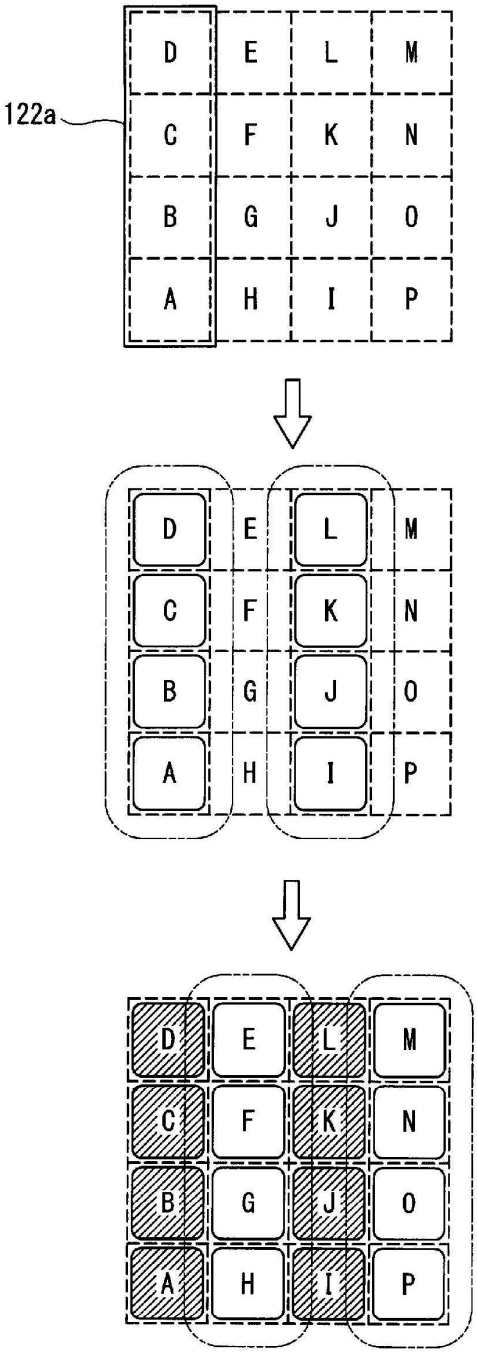
122a
D E L M
C F K N
B G J O
A H I P
D E L M
C F K N
B G J O
A H I P
D E L M
C F K N
B G J O
A H I P

FIG. 11